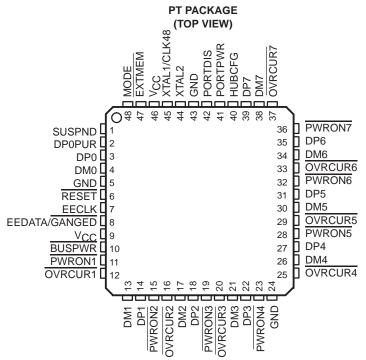


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- Fully Compliant With the USB Specification as a Full-Speed Hub: TID #20240226
- Integrated USB Transceivers
- 3.3-V Low-Power ASIC Logic
- Two Power Source Modes
 - Self-Powered Mode Supporting Seven Downstream Ports
 - Bus-Powered Mode Supporting Four Downstream Ports
- All Downstream Ports Support Full-Speed and Low-Speed Operations
- Power Switching and Overcurrent Reporting Is Provided Per Port or Ganged
- Supports Suspend and Resume Operations
- Suspend Status Terminal Available for External Logic Power Down
- Supports Custom Vendor ID and Product ID With External Serial EEPROM
- 3-State EEPROM Interface to Allow EEPROM Sharing

- Push-Pull Outputs for PWRON Eliminate the Need for External Pullup Resistors
- Noise Filtering on OVRCUR Provides Immunity to Voltage Spikes
- Supports 6-MHz Operation Through Crystal Input or 48-MHz Input Clock
- New Functional Terminals Introduced to Reduce the Board Material Cost
 - 3 LED Indicator Control Outputs Enable Visualized Monitoring of 6 Different Hub/Port Status (HUBCFG, PORTPWR, PORTDIS)
 - Output Terminal Available to Disable External Pullup Resistor on DP0 for 15 ms After Reset or After Change on BUSPWR and Enable Easy Implementation of Onboard Bus/Self-Power Dynamic Switching Circuitry
- Available in 48-Terminal LQFP[†] Package



NC - No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

JEDEC descriptor S-PQFP-G for low-profile quad flatpack (LQFP)



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description

The TUSB2077A hub is a 3.3-V CMOS device that provides up to seven downstream ports in compliance with the USB version 1.1 specification. Because this device is implemented with a digital state machine instead of a microcontroller, no software programming is required. Fully-compliant USB transceivers are integrated into the ASIC for all upstream and downstream ports. The downstream ports support both full-speed and low-speed devices by automatically setting the slew rate according to the speed of the device attached to the ports. The configuration of the BUSPWR terminal selects either the bus-powered or self-powered mode. The introduction of the DP0 pullup resistor disable terminal, DP0PUR, makes it much easier to implement an onboard bus/self-power dynamic-switching circuitry. The three LED indicator control output terminals also enable the implementation of visualized status monitoring of the hub and its downstream ports. With these new function terminals, the end equipment vendor can considerably reduce the total board cost while adding additional product value.

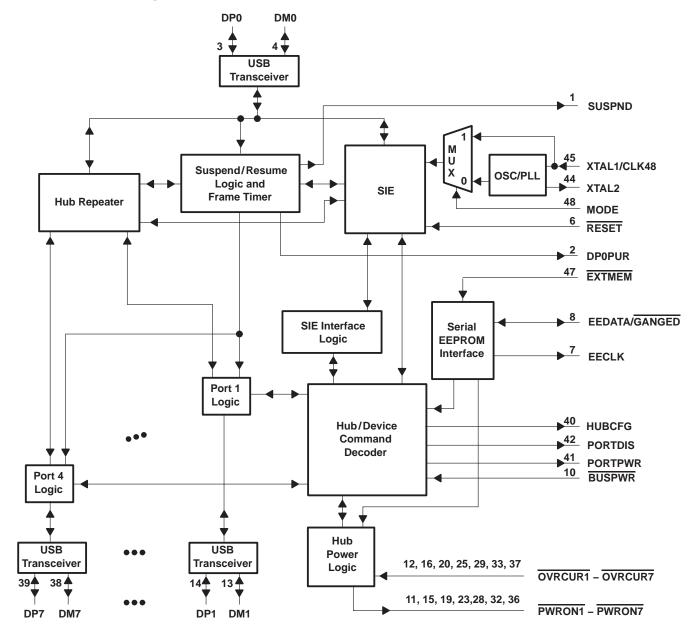
The EXTMEM (terminal 47) enables or disables the optional EEPROM interface. When EXTMEM is high, the vendor and product IDs (VID and PID) use defaults, such that the message displayed during enumeration is *General Purpose USB Hub*. For this configuration, terminal 8 functions as the <u>GANGED</u> input terminal and <u>EECLK</u> (terminal 7) is unused. If custom VID and PID descriptors are desired, the <u>EXTMEM</u> must be tied low (<u>EXTMEM</u> = 0) and a SGS Thompson M93C46 EEPROM, or equivalent, stores the programmable VID, PID, and <u>GANGED</u> values. For this configuration, terminals 7 and 8 function as the EEPROM interface signals with terminal 7 as EECLK and terminal 8 as EEDATA, respectively.

The TUSB2077A supports both bus-powered and self-powered modes. External power-management devices, such as the TPS2044, are required to control the 5-V power source switching (on/off) to the downstream ports and to detect an overcurrent condition from the downstream ports individually or ganged. Outputs from external power devices provide overcurrent inputs to the TUSB2077A OVRCUR terminals in case of an overcurrent condition, the corresponding PWRON terminals are disabled by the TUSB2077A. In the ganged mode, all PWRON signals transition simultaneously, and any OVRCUR input can be used. In the nonganged mode, the PWROR outputs and OVRCUR inputs operate on a per-port basis.

The TUSB2077A provides the flexibility of using either a 6-MHz or a 48-MHz clock. The logic level of the MODE terminal controls the selection of the clock source. When MODE is low, the output of the internal APLL circuitry is selected to drive the internal core of the chip. When MODE is high, the XTAL1 input is selected as the input clock source and the APLL circuitry is powered down and bypassed. The internal oscillator cell is also powered down while MODE is high. For 6-MHz operation, TUSB2077A requires a 6-MHz clock signal on XTAL1 terminal (with XTAL2 for a crystal) from which its internal APLL circuitry generates a 48-MHz internal clock to sample the data from the upstream port. For 48-MHz operation, the clock cannot be generated with a crystal, using the XTAL2 output, since the internal oscillator cell only supports the fundamental frequency. If low-power suspend and resume are desired, a passive crystal or resonator must be used, although the hub supports the flexibility of using any device that generates a 6-MHz clock. Because most oscillators cannot be stopped while power is on, their use prohibits low-power suspend, which depends on disabling the clock. When the oscillator is used, by connecting its output to the XTAL1 terminal and leaving the XTAL2 terminal open, its TTL output level can not exceed 3.6 V. If a 6-MHz oscillator is used, it must be stopped at logic low whenever SUSPND is high. For crystal or resonator implementations, the XTAL1 terminal is the input and the XTAL2 terminal is used as the feedback path. A sample crystal tuning circuit is shown in Figure 7.



functional block diagram



Terminal Functions

TER	MINAL		
NAME	NO.	1/0	DESCRIPTION
BUSPWR	10	I	Power source indicator. BUSPWR is an active-low input that indicates whether the downstream ports source their power from the USB cable or a local power supply. For the bus-power mode, this terminal must be pulled low; and for the self-powered mode, this terminal must be pulled to 3.3 V. Input must not change dynamically during operation.
DM0	4	I/O	Root port USB differential data minus. DM0 paired with DP0 constitutes the upstream USB port.
DM1 – DM7	13, 17, 21, 26, 30, 34, 38	I/O	USB differential data minus. DM1 – DM7 paired with DP1 – DP7 support up to seven downstream USB ports.
DP0	3	I/O	Root port USB differential data plus. DP0 paired with DM0 constitutes the upstream USB port.
DP1 – DP7	14, 18, 22, 27, 31, 35, 39	I/O	USB differential data plus. DP1 – DP7 paired with DM1 – DM7 support up to seven downstream USB ports.
DP0PUR	2	0	Pullup resistor connection. When a <u>system reset</u> happens (RESET being driven to low, but not USB reset) or any logic level change on <u>BUSPWR</u> terminal, DP0PUR output is inactive (floating) until the internal counter reaches a 15-ms time period. After the counter expires, DP0PUR is driven to the V _{CC} (3.3 V) level thereafter until the next system reset event occurs or there is a <u>BUSPWR</u> logic level change.
EECLK	7	0	EEPROM serial clock. When EXTMEM is high, the EEPROM interface is disabled. The EECLK terminal is disabled and must be left floating (unconnected). When EXTMEM is low, EECLK acts as a 3-state serial clock output to the EEPROM with a 100-μA internal pulldown.
EEDATA/ GANGED	8	I/O	EEPROM serial data/power management mode indicator. When EXTMEM is low, EEDATA/GANGED acts as a serial data I/O for the EEPROM and is internally pulled down with a 100-μA pulldown. When EXTMEM is high, EEDATA/GANGED selects between ganged or per-port power overcurrent detection for the downstream ports. This standard TTL input must not change dynamically during operation.
EXTMEM	47	I	EEPROM read enable. When EXTMEM is high, the serial EEPROM interface of the device is disabled. When EXTMEM is low, terminals 7 and 8 are configured as the clock and data terminals of the serial EEPROM interface, respectively.
GND	5, 24, 43		Ground. GND terminals must be tied to ground for proper operation.
HUBCFG [†]	40	0	Hub configured. Used to control LED indicator. When the hub is configured, HUBCFG is high, which can be used to turn on a green LED. When the hub is not configured, HUBCFG is low, which can be used to turn on a red LED.
MODE	48	I	Mode select. When MODE is low, the APLL output clock is selected as the clock source to drive the internal core of the chip and 6-MHz crystal or oscillator can used. When MODE is high, the clock on XTAL1/CLK48 is selected as the clock source and 48-MHz oscillator or other onboard clock source can be used.
OVRCUR1 – OVRCUR7	12, 16, 20, 25, 29, 33, 37	I	Overcurrent input. OVRCUR1 – OVRCUR7 are active low. For per-port overcurrent detection, one overcurrent input is available for each of the seven downstream ports. In the ganged mode, any OVRCUR input may be used and all OVRCUR terminals must be tied together. OVRCUR terminals have noise filtering logic.
PORTPWR†	41	0	Any port powered. Used to control LED indicator. When any port is powered on, PORTPWR is high, which can be used to turn on a green LED. When all ports are off, PORTPWR is low, which can be used to turn on a red LED.
PORTDIS†	42	0	No ports disabled. PORTDIS is used for LED indicator control. When no port is disabled, PORTDIS is high, which can be used to turn on a green LED. When any port is disabled, PORTDIS is low, which can be used to turn on a red LED.
PWRON1 – PWRON7	11, 15, 19, 23, 28, 32, 36	0	Power-on/-off control signals. PWRON1 – PWRON7 are active low, push-pull outputs that enables the external power switch device. Push-pull outputs eliminate the pullup resistors which are required by for open-drain outputs. However, the external power switches that connect to these terminals must be able to operate with 3.3-V inputs because these outputs cannot drive 5-V signals.
RESET	6	I	Reset. RESET is an active low TTL input with hysteresis and must be asserted at power up. When RESET is asserted, all logic is initialized. Generally, a reset with a pulse width between 100 μ s and 1 ms is recommended after 3.3-V V _{CC} reaches its 90%. The clock signal must be active during the last 60 μ s of the reset window.



Terminal Functions (Continued)

TERMINAL			
NAME	NO.	1/0	DESCRIPTION
SUSPND	1	0	Suspend status. SUSPND is an active-high output available for external logic power-down operations. During the SUSPEND mode, SUSPND is high. SUSPND is low for normal operation.
VCC	9, 46		3.3-V supply voltage.
XTAL1/CLK48	45	I	Crystal 1/48-MHz clock input. When MODE is low, XTAL1/CLK48 is a 6-MHz crystal input with 50% duty cycle. An internal APLL generates the 48-MHz and 12-MHz clocks used internally by the ASIC logic. When MODE is high, XTAL1/CLK48 acts as the input of the 48-MHz clock and the internal APLL logic is bypassed.
XTAL2	44	0	Crystal 2. XTAL2 is a 6-MHz crystal output. This terminal must be left open when using an oscillator.

[†] All LED control are 3-stated during low-power suspend.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.5 V to 3.6 V
Input voltage range, V _I	-0.5 V to $V_{CC} + 0.5 \text{ V}$
Output voltage range, VO	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} , $(V_I < 0 \text{ V or } V_I > V_{CC})$	±20 mA
Output clamp current, I_{OK} , $(V_O < 0 \text{ V or } V_O > V_{CC})$	±20 mA
Storage temperature range, T _{stg}	–65°C to 150°C
Operating free-air temperature range, T _A	0°C to 70°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage levels are with respect to GND.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	3	3.3	3.6	V
Input voltage, TTL/LVCMOS‡, VI	0		VCC	V
Output voltage, TTL/LVCMOS§, VO	0		VCC	V
High-level input voltage, signal-ended receiver, VIH(REC)	2		Vcc	V
Low-level input voltage, signal-ended receiver, VIL(REC)			0.8	V
High-level input voltage, TTL/LVCMOS‡, VIH(TTL)	2		VCC	V
Low-level input voltage, TTL/LVCMOS‡, V _{IL(TTL)}	0		0.8	V
Operating free-air temperature, T _A	0		70	°C
External series, differential driver resistor, R(DRV)		22		Ω
Operating (DC differential driver) high speed mode, f(OPRH)			12	Mb/s
Operating (DC differential driver) low speed mode, f(OPRL)			1.5	Mb/s
Common mode, input range, differential receiver, V(ICR)	0.8		2.5	V
Input transition times (t _r and t _f), TTL/LVCMOS‡	0		25	ns
Junction temperature range, TJ¶	0		115	°C

[‡] Applies for input and bidirectional buffers



[§] Applies for output and bidirectional buffers

These junction temperatures reflect simulated conditions. Absolute maximum junction temperature is 150°C. The customer is responsible for verifying junction temperature.

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electrical characteristics over recommended ranges of operating free-air temperature and supply voltage (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
		TTL/LVCMOS	$I_{OH} = -4 \text{ mA}$	V _{CC} - 0.5		
VOH	High-level output voltage	LIOD data lines	$R_{(DRV)} = 15 \text{ k}\Omega$, to GND	2.8		V
		USB data lines	$I_{OH} = -12 \text{ mA (without R}_{(DRV)})$	V _{CC} - 0.5		
		TTL/LVCMOS	I _{OL} = 4 mA		0.5	
VOL	Low-level output voltage	USB data lines	$R(DRV) = 1.5 \text{ k}\Omega \text{ to } 3.6 \text{ V}$		0.3	V
		USB data lines	$I_{OL} = 12 \text{ mA (without R}_{(DRV)})$		0.5	
\/	Docitive input threshold voltage	TTL/LVCMOS			1.8	V
V _{IT+}	Positive input threshold voltage	Single-ended	$0.8 \text{ V} \leq \text{V}_{\text{ICR}} \leq 2.5 \text{ V}$		1.8	V
\/	Negative input threehold veltage	TTL/LVCMOS		0.8		V
V _{IT} _	Negative-input threshold voltage	Single-ended	$0.8 \text{ V} \le \text{V}_{1CR} \le 2.5 \text{ V}$	1		V
.,	land bustons dist (V = V = V	TTL/LVCMOS		0.3	0.7	V
V _{hys}	Input hysteresis† (V _{T+} – V _{T-})	Single-ended	$0.8 \text{ V} \le \text{V}_{1CR} \le 2.5 \text{ V}$	300	500	mV
	I lieb in a decree autout account	TTL/LVCMOS	V = V _{CC} or GND‡		±10	μΑ
loz	High-impedance output current	USB data lines	$0 \text{ A} \leq \text{AO} \leq \text{ACC}$		±10	μΑ
I _I L	Low-level input current	TTL/LVCMOS	V _I = GND		-1	μΑ
lН	High-level input current	TTL/LVCMOS	VI = VCC		1	μΑ
z _o (DRV)	Driver output impedance	USB data lines	Static VOH or VOL	7.1	19.9	Ω
V _{ID}	Differential input voltage	USB data lines	0.8 V ≤ V _{ICR} ≤ 2.5 V	0.2		V
	land complete compart		Normal operation		40	mA
lcc	Input supply current		Suspend mode		1	μΑ

[†] Applies for input buffers with hysteresis

differential driver switching characteristics over recommended ranges of operating free-air temperature and supply voltage, $C_L = 50$ pF (unless otherwise noted)

full speed mode

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
t _r	Transition rise time for DP or DM	See Figure 1 and Figure 2	4	20	ns
tf	Transition fall time for DP or DM	See Figure 1 and Figure 2	4	20	ns
t(RFM	Rise/fall time matching§	$(t_{\Gamma}/t_{f}) \times 100$	90%	110%	
VO(CRS)	Signal crossover output voltage§		1.3	2.0	V

[§] Characterize only. Limits are approved by design and are not production tested.

low speed mode

	PARAMETER	TEST (TEST CONDITIONS				
t _r	Transition rise time for DP or DM§	$C_L = 200 \text{ pF to } 600 \text{ pF},$	See Figure 1 and Figure 2	75	300	ns	
t _f	Transition fall time for DP or DM§	$C_L = 200 \text{ pF to } 600 \text{ pF},$	See Figure 1 and Figure 2	75	300	ns	
t(RFM)	Rise/fall time matching§	$(t_{r}/t_{f}) \times 100$		80%	120%		
VO(CRS)	Signal crossover output voltage§	C _L = 200 pF to 600 pF		1.3	2.0	V	

[§] Characterize only. Limits are approved by design and are not production tested.



[‡] Applies for open drain buffers

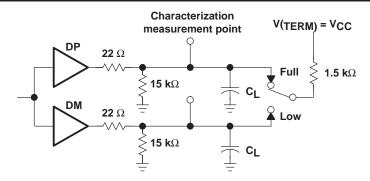
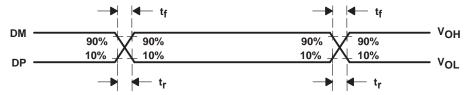


Figure 1. Differential Driver Switching Load



NOTE: The t_f/t_f ratio is measured as $t_f(DP)/t_f(DM)$ and $t_f(DM)/t_f(DP)$ at each crossover point.

Figure 2. Differential Driver Timing Waveforms

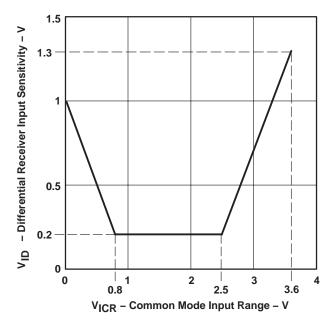


Figure 3. Differential Receiver Input Sensitivity vs. Common Mode Input Range

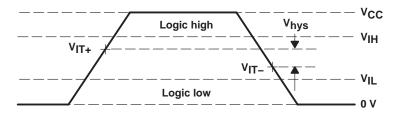


Figure 4. Single-Ended Receiver Input Signal Parameter Definitions



APPLICATION INFORMATION

A major advantage of USB is the ability to connect 127 functions configured in up to 6 logical layers (tiers) to a single personal computer (see Figure 5)

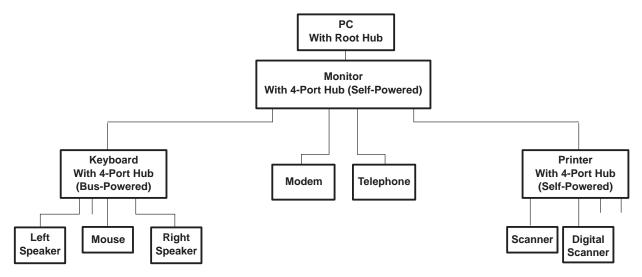


Figure 5. USB-Tiered Configuration Example

Another advantage of USB is that all peripherals are connected using a standardized four-wire cable that provides both communication and power distribution. The power configurations are bus-powered and self-powered modes. The maximum current that may be drawn from the USB 5-V line during power up is 100 mA. For the bus-powered mode, a hub can draw a maximum of 500 mA from the 5-V line of the USB cable. A bus-powered hub must always be connected downstream to a self-powered hub unless it is the only hub connected to the PC and there are no high-powered functions connected downstream. In the self-powered mode, the hub is connected to an external power supply and can supply up to 500 mA to each downstream port. High-powered functions may draw a maximum of 500 mA from each downstream port and may only be connected downstream to self-powered hubs. Per the USB specification, in the bus-powered mode, each downstream port can provide a maximum of 100 mA of current, and in the self-powered mode, each downstream port can provide a maximum of 500 mA of current.

Both bus-powered and self-powered hubs require overcurrent protection for all downstream ports. The two types of protection are individual-port management (individual-port basis) or ganged-port management (multiple-port basis). Individual-port management requires power-management devices for each individual downstream port, but adds robustness to the USB system because, in the event of an overcurrent condition, the USB host only powers down the port that has the condition. The ganged-port configuration uses fewer power management devices and thus has lower system costs, but in the event of an overcurrent condition on any of the downstream ports, all the ganged ports are disabled by the USB host.

Using a combination of the BUSPWR and EEDATA/GANGED inputs, the TUSB2077A supports four modes of power management: bus-powered hub with either individual-port power management or ganged-port power management, and the self-powered hub with either individual-port power management or ganged-port power management. Texas Instruments supplies the complete hub solution because we offer this TUSB2077A, the TUSB2046 (4-port), and the TUSB2140B (4-port with I²C) hubs along with the power-management devices needed to implement a fully USB Specification 1.1-compliant system.



APPLICATION INFORMATION

The following sections provide block diagram examples of how to implement the TUSB2077A device. Please note, even though no resistors are shown, pullup, pulldown, and series resistors must still be used to properly implement this device.

Figure 6 is a block diagram example of how to connect the external EEPROM if a custom product ID and vendor ID are desired.

Figure 7 is an example of how to generate the 6-MHz clock signal. Figure 8 shows the EEPROM read operation timing diagram. Figures 9, 10, and 11 illustrate how to connect the TUSB2077A device for different power source and port power-management combinations.

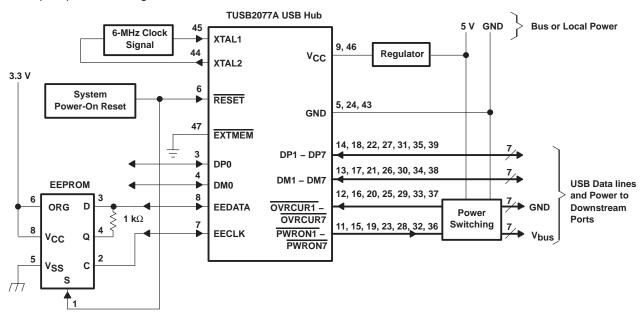
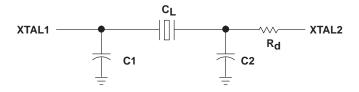


Figure 6. Typical Application of the TUSB2077A USB Hub



NOTE A: Figure 7 assumes a 6 MHz fundamental crystal that is parallel loaded. The component values of C1, C2 and R_d were determined using a crystal from Fox Electronics – part number HC49U–6.00MHz30\50\0 \pm 70\20 which means \pm 30 ppm at 25°C and 50 ppm from 0°C to 70°C. The characteristics for the crystal are load capacitance (C_L) of 20 pF, maximum shunt capacitance (C₀) of 7 pF and the maximum ESR of 50 Ω . In order to insure enough negative resistance, use C1 = C2 = 27 pF. The resistor R_d is used to trim the gain, and R_d = 1.5 k Ω is recommended.

Figure 7. Crystal Tuning Circuit



APPLICATION INFORMATION

programming the EEPROM

An SGS Thompson M93C46 EEPROM, or equivalent, is used for storing the programmable VID and PID. When the EEPROM interface is enabled ($\overline{\text{EXTMEM}} = 0$), the EECLK and EEDATA are internally pulled down (100 μ A) inside the TUSB2077A. The internal pulldowns are disabled when the EEPROM interface is disabled ($\overline{\text{EXTMEM}} = 1$).

The EEPROM is programmed with the three 16-bit locations as shown in Table 1. Connecting terminal 6 of the EEPROM high (ORG = 1) organizes the EEPROM memory into 64×16-bit words.

Table 1. EEPROM Memory Map

ADDRESS	D15	D14	D13	D12-D8	D7-D0
00000	0	GANGED	00000	00000	00000000
00001		VID H	ligh-byte		VID Low-byte
00010		PID F	ligh-byte		PID Low-byte
			XXXXX	XXX	

The D and Q signals of the EEPROM must be tied together using a $1-k\Omega$ resistor with the common I/O operations forming a single-wire bus. After system power-on reset, the TUSB2077A performs a one-time access read operation from the EEPROM if the EXTMEM terminal is pulled low and the chip select(s) of the EEPROM is connected to the system power-on reset. Initially, the EEDATA terminal is driven by the TUSB2077A to send a start bit (1) which is followed by the read instruction (10) and the starting-word address (00000). Once the read instruction is received, the instruction and address are decoded by the EEPROM, which then sends the data to the output shift register. At this point, the hub stops driving the EEDATA terminal and the EEPROM starts driving. A dummy (0) bit is then output and the first three 16-bit words in the EEPROM are output with the most significant bit (MSB) first.

The output data changes are triggered by the rising edge of the clock provided by the TUSB2077A on the EECLK terminal. The SGS-Thompson M936C46 EEPROM is recommended because it advances to the next memory location by automatically incrementing the address internally. Any EEPROM used must have the automatic internal address advance function. After reading the three words of data from the EEPROM, the TUSB2077A puts the EEPROM interface into a high-impedance condition (pulled down internally) to allow other logic to share the EEPROM. The EEPROM read operation is summarized in Figure 8. For more details on EEPROM operation, refer to SGS-Thompson Microelectronics M93C46 Serial Microwire Bus EEPROM data sheet.



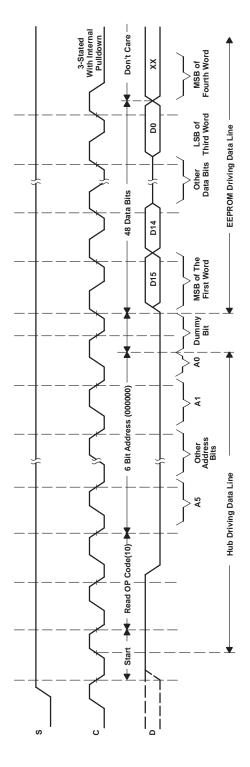


Figure 8. EEPROM Read Operation Timing Diagram



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APPLICATION INFORMATION

bus-powered hub, ganged-port power management

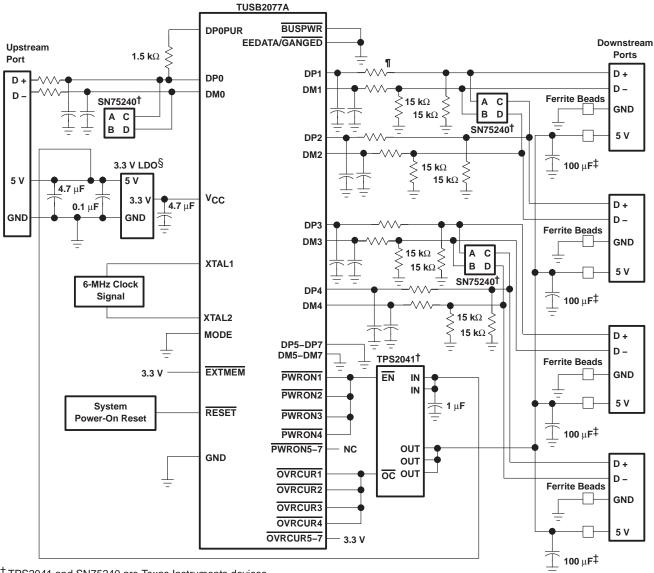
When used in bus-powered mode, the TUSB2077A supports up to four downstream ports by controlling a TPS2041 device which is capable of supplying 100 mA of current to each downstream port. Bus-powered hubs must implement power switching to ensure current demand is held below 100 mA when the hub is hot-plugged into the system. Utilizing the TPS2041 for ganged-port power management provides overcurrent protection for the downstream ports. The SN75240 transient suppressors reduce inrush current and voltage spikes on the data lines. The OVRCUR signals must be tied together for a ganged operation.



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APPLICATION INFORMATION

bus-powered hub, ganged-port power management (continued)



[†] TPS2041 and SN75240 are Texas Instruments devices.

Figure 9. TUSB2077A Bus-Powered Hub, Ganged-Port Power-Management Application

^{‡ 120} μF per hub is the minimum required per the USB specification, version 1.1. However, TI recommends a 100-μF, low ESR, tantalum capacitor per port for immunity to voltage droop.

^{\$} LDO is a 5-V-to-3.3-V voltage regulator. TPS76333 from Texas Instruments can be used.

 $[\]P$ All USB DP, DM signal pairs require series resistors of approximately 27 Ω to ensure proper termination. An optional filter capacitor of about 22 pF is recommended for EMI suppression. This capacitor, if used, must be placed between the hub pin and the series resistor, as per section 7.1.6 of the USB specification.

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APPLICATION INFORMATION

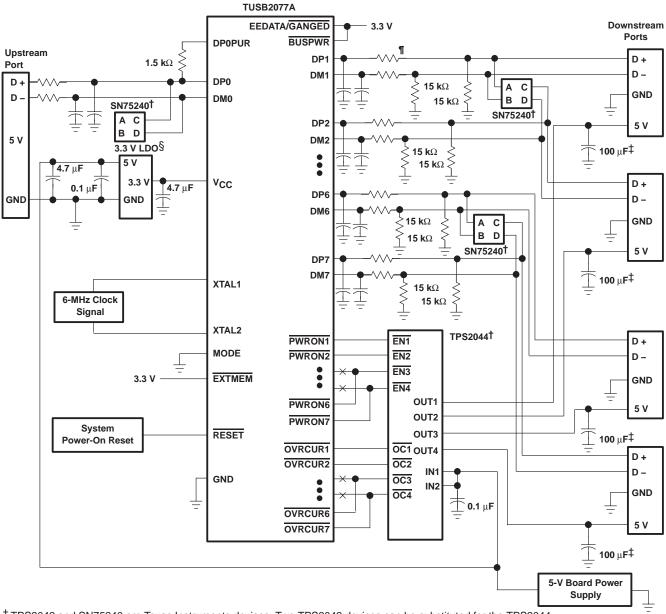
self-powered hub, individual-port power management

In a self-powered configuration, the TUSB2077A can be implemented for individual-port power management when used with two TPS2044 because it is capable of supplying 500 mA of current to each downstream port and can provide current limiting on a per port basis. When the hub detects a fault on a downstream port, power is removed from only the port with the fault and the remaining ports continue to operate normally. Self-powered hubs are required to implement overcurrent protection and report overcurrent conditions. The SN75240 transient suppressors reduce inrush current and voltage spikes on the data lines.



APPLICATION INFORMATION

self-powered hub, individual-port power management (continued)



[†]TPS2042 and SN75240 are Texas Instruments devices. Two TPS2042 devices can be substituted for the TPS2044.

Figure 10. TUSB2077A Self-Powered Hub, Individual-Port Power-Management Application



^{‡120} μF per hub is the minimum required per the USB specification, version 1.1. However, TI recommends a 100-μF, low ESR, tantalum capacitor per port for immunity to voltage droop.

^{\$} LDO is a 5-V-to-3.3-V voltage regulator. TPS76333 from Texas Instruments can be used.

[¶] All USB DP, DM signal pairs require series resistors of approximately 27 Ω to ensure proper termination. An optional filter capacitor of about 22 pF is recommended for EMI suppression. This capacitor, if used, must be placed between the hub pin and the series resistor, as per section 7.1.6 of the USB specification.

SLLS414A - MARCH 2000 - REVISED DECEMBER 2004

APPLICATION INFORMATION

self-powered hub, ganged-port power management

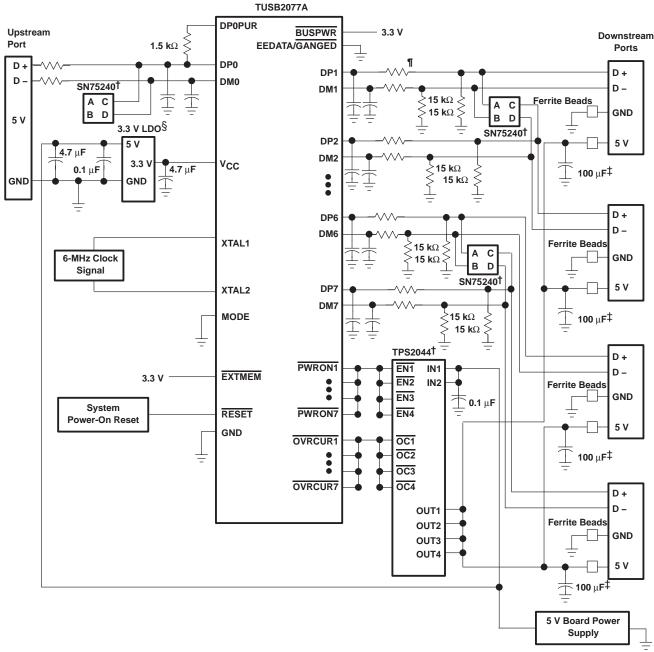
The TUSB2077 can also be implemented for ganged-port power management in a self-powered configuration. The implementation is very similar to the bus-powered example with the exception that a self-powered port supplies 500 mA of current to each downstream port. The overcurrent protection can be provided by a TPS2044 quad device or a TPS2024 single power switch.



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APPLICATION INFORMATION

self-powered hub, ganged-port power management (continued)



[†]TPS2044, TPS2042, and SN75240 are Texas Instruments devices. The TPS2024 can be substituted for the TPS2044.

Figure 11. TUSB2077A Self-Powered Hub, Ganged-Port Power-Management Application



^{‡ 120} μF per hub is the minimum required per the USB specification, version 1.1. However, TI recommends a 100-μF, low ESR, tantalum capacitor per port for immunity to voltage droop.

^{\$} LDO is a 5-V-to-3.3-V voltage regulator. TPS76333 from Texas Instruments can be used.

[¶] All USB DP, DM signal pairs require series resistors of approximately 27 Ω to ensure proper termination. An optional filter capacitor of about 22 pF is recommended for EMI suppression. This capacitor, if used, must be placed between the hub pin and the series resistor, as per section 7.1.6 of the USB specification.





.com 20-Mar-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TUSB2077APT	ACTIVE	LQFP	PT	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TUSB2077APTR	ACTIVE	LQFP	PT	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TUSB2077APTRG4	ACTIVE	LQFP	PT	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

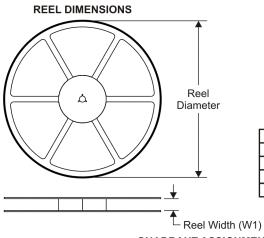
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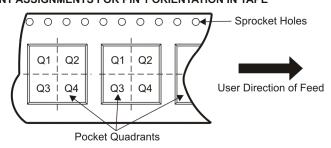
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

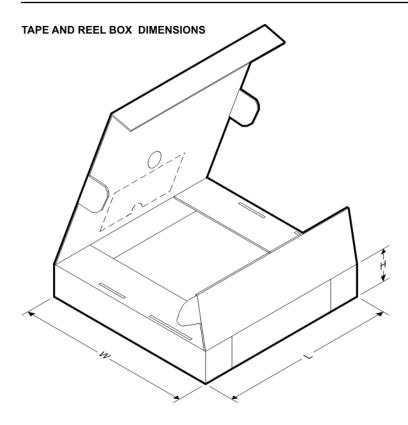
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TUSB2077APTR	LQFP	PT	48	1000	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q2



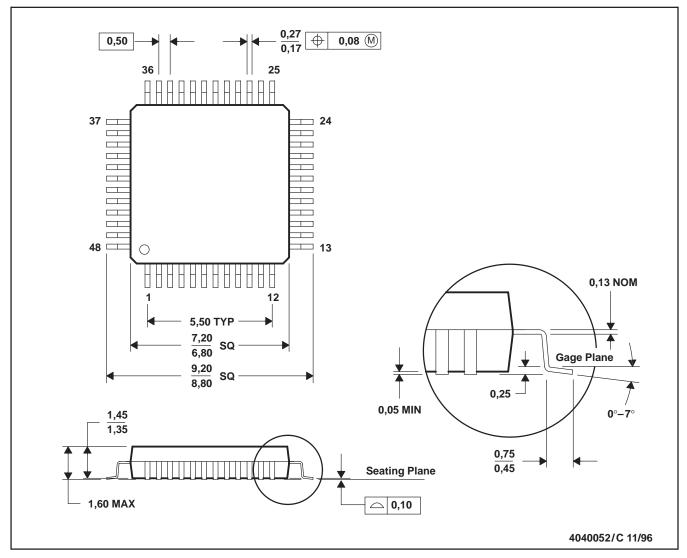


*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
I	TUSB2077APTR	LQFP	PT	48	1000	346.0	346.0	33.0

PT (S-PQFP-G48)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-026
- D. This may also be a thermally enhanced plastic package with leads conected to the die pads.

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